

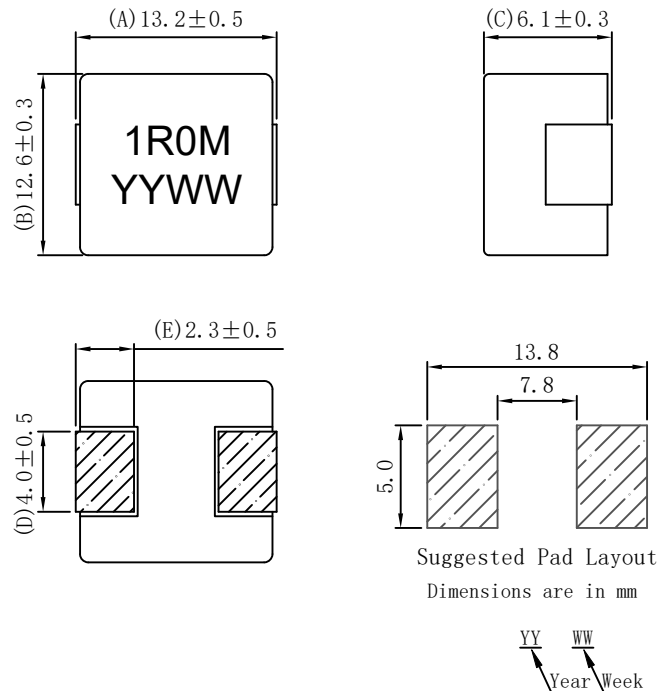
FEATURES

- RoHS compliant
- Small size (13.7*12.9mm Max),low profile(Height:6.4mm Max)
- Inductance range from 0.10uH to 10.0uH
- Surface mount design
- Magnetic shield construction
- Ultra low buzz noise due to composite construction
- Handle transient current spikes without saturation
- UL94V-0
- Tape & reel packing
- Solder profile acc.J-STD-020D

APPLICATIONS

- Low profile ,high current power supplies
- DC/DC converters
- Battery powered devices
- PDA/notebook/desktop/server applications

Part number	Inductance (μ H \pm 20%)	DCR TYP. (m Ω)	DCR MAX. (m Ω)	I _{rms} (A)	I _{sat} (A)
MHC1264SGR10M	0.10	0.47	0.50	60.0	120.0
MHC1264SGR15M	0.15	0.53	0.60	55.0	118.0
MHC1264SGR22M	0.22	0.63	0.70	53.0	112.0
MHC1264SGR30M	0.30	0.70	0.80	48.0	72.0
MHC1264SGR33M	0.33	0.83	0.90	46.0	65.0
MHC1264SGR40M	0.40	0.90	1.0	44.0	64.0
MHC1264SGR47M	0.47	1.0	1.2	41.0	63.0
MHC1264SGR56M	0.56	1.2	1.4	37.0	62.0
MHC1264SGR68M	0.68	1.4	1.6	35.0	60.0
MHC1264SGR82M	0.82	1.6	1.9	33.0	50.0
MHC1264SG1R0M	1.0	1.7	2.0	32.0	49.0
MHC1264SG1R2M	1.2	2.1	2.5	30.0	48.0
MHC1264SG1R5M	1.5	2.5	3.0	27.0	45.0
MHC1264SG1R8M	1.8	2.8	3.2	24.0	41.0
MHC1264SG2R2M	2.2	3.5	4.2	22.0	40.0
MHC1264SG3R3M	3.3	5.7	6.8	18.0	35.0
MHC1264SG4R7M	4.7	8.0	8.7	13.5	32.0
MHC1264SG5R6M	5.6	9.3	10.0	12.5	30.0
MHC1264SG6R8M	6.8	13.1	14.0	11.5	16.5
MHC1264SG8R2M	8.2	14.5	15.5	10.5	16.0
MHC1264SG100M	10.0	16.4	17.2	10.0	15.5



ABSOLUTE MAXIMUM RATINGS

Operating temperature rang	-55°C to +125°C
(Including coil' self temperature rise)	
Storage temperature rang	-55°C to +125°C

SOLDERING INFORMATION

Peak reflow temperature	250°C
Pin finish	tin

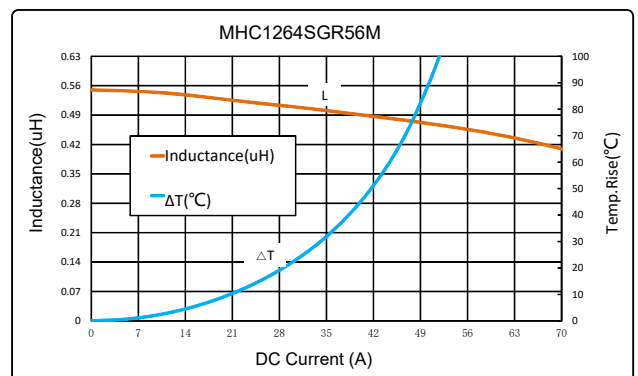
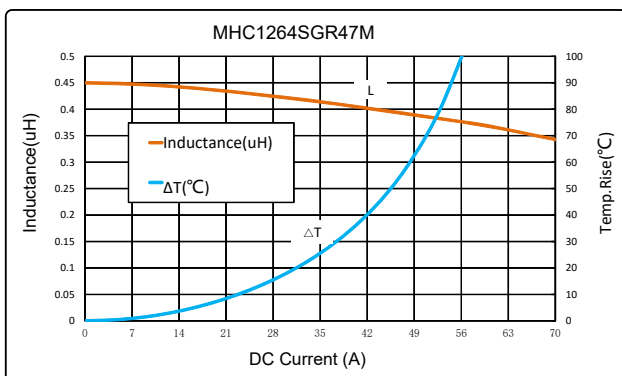
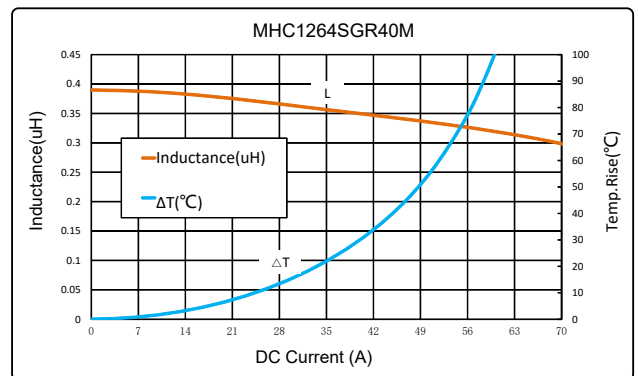
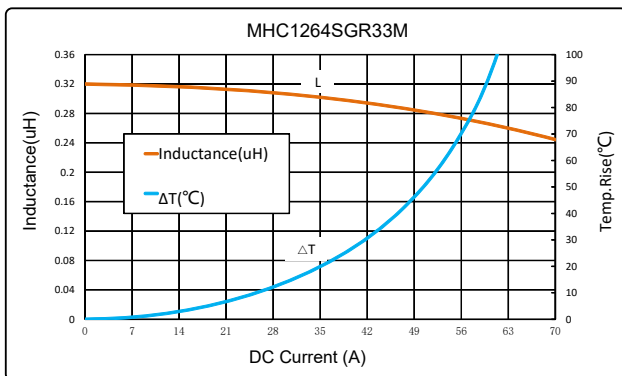
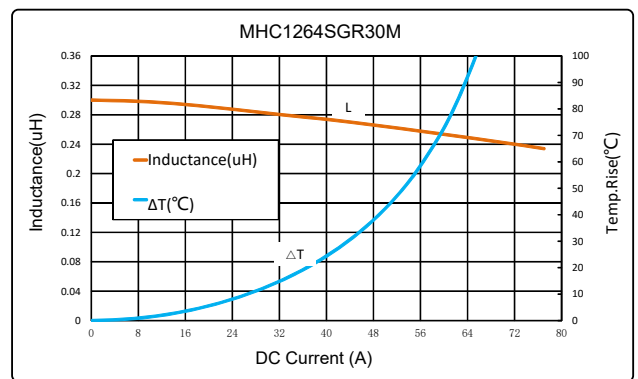
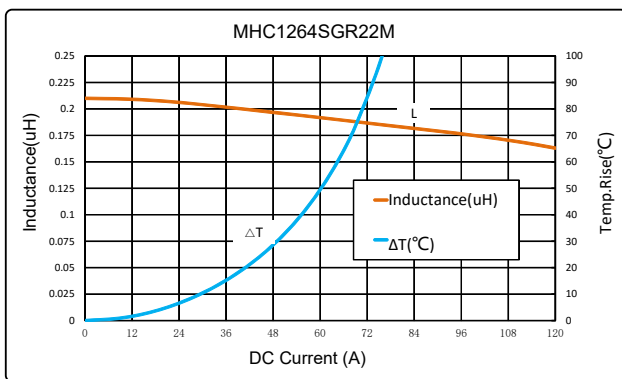
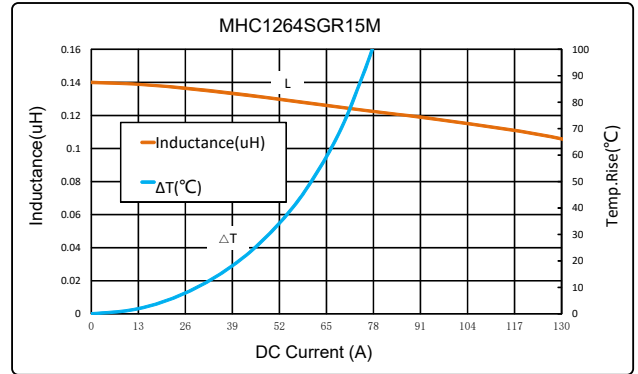
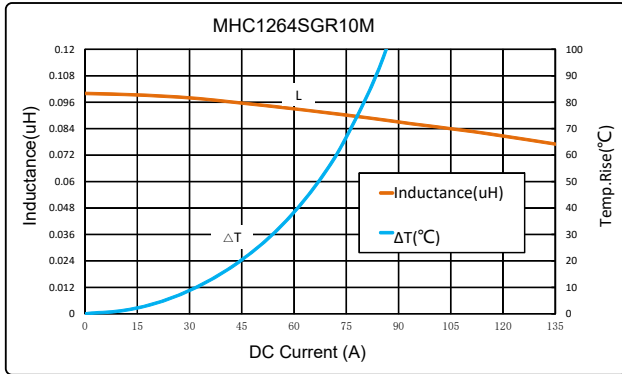
PACKAGING INFORMATION

Tape&Reel	300pcs per reel
Weight	6.0g/pcs

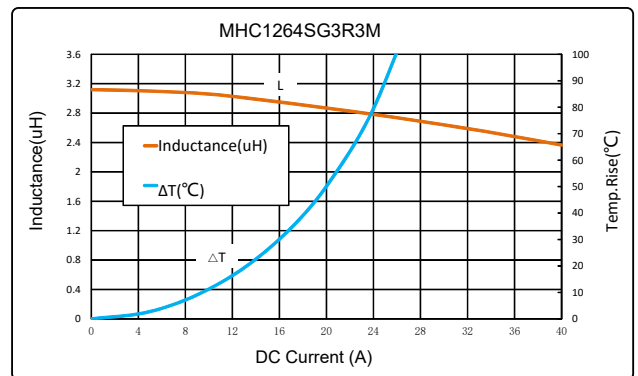
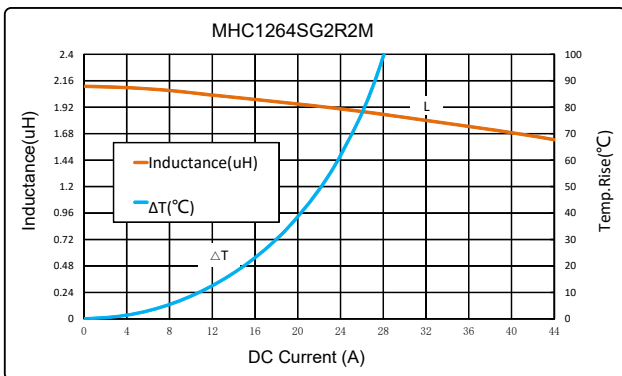
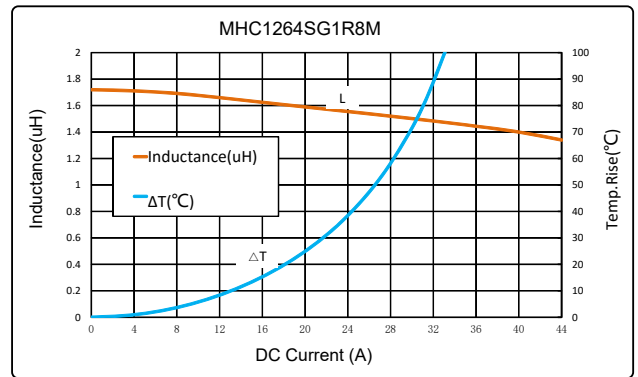
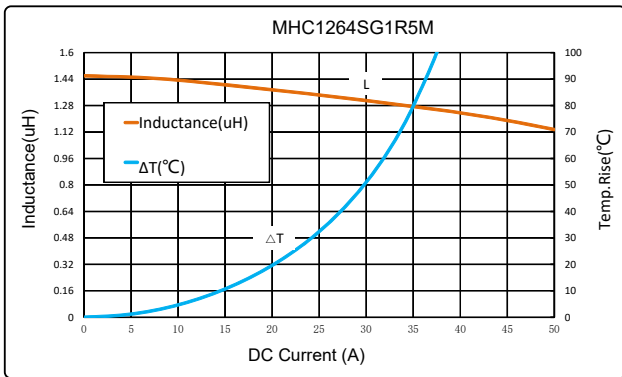
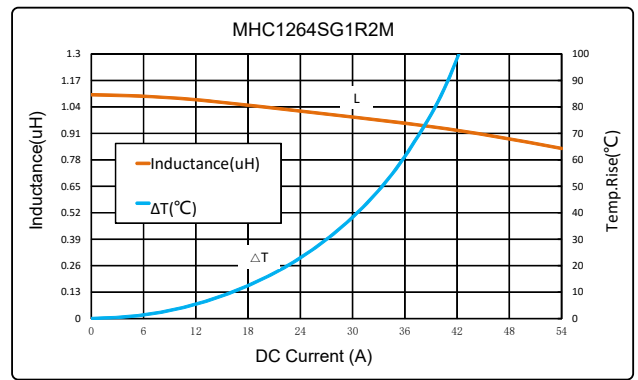
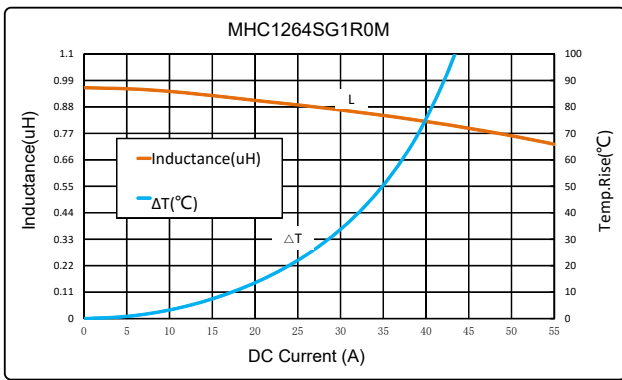
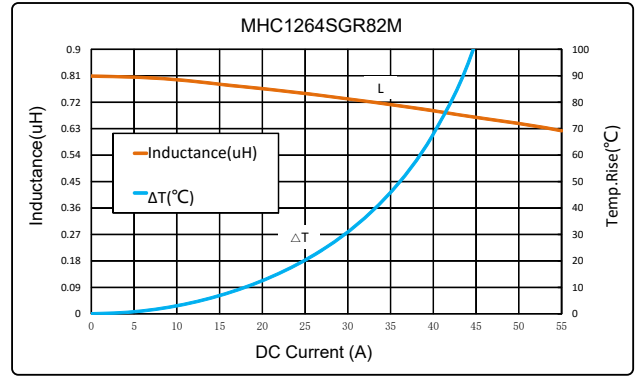
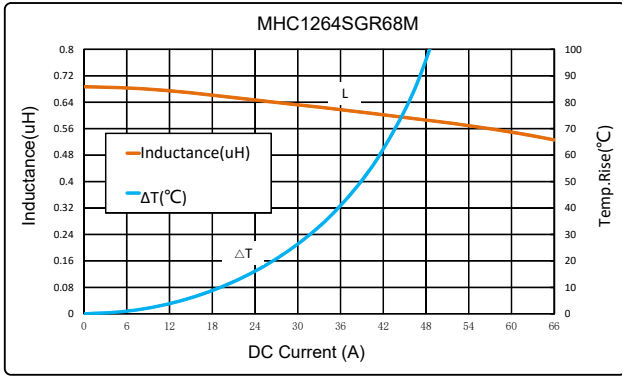
Notes

1. Electrical specification at 25°C.
2. Inductance tested at 100 kHz, 0.25Vrms.
3. I_{rms} is the current that caused a approximate 40°C temperature rise from 25°C ambient.
4. I_{sat} is the DC current at which inductance drop approximately 20% from its value without current.
5. The part temperature(ambient + temp.rise) should not exceed 125°C under worst case operating conditions.Circuit design,component placement, PWB trace size and thickness,airflow and other cooling provisions all affect the part temperature.Part temperature should be verified in the end application.

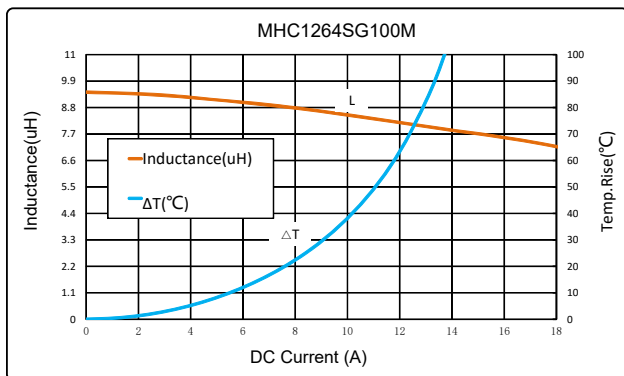
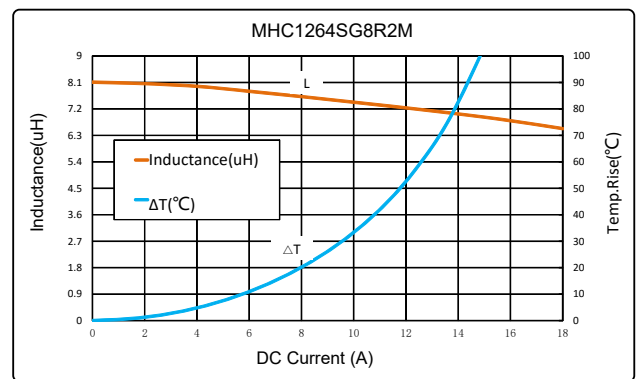
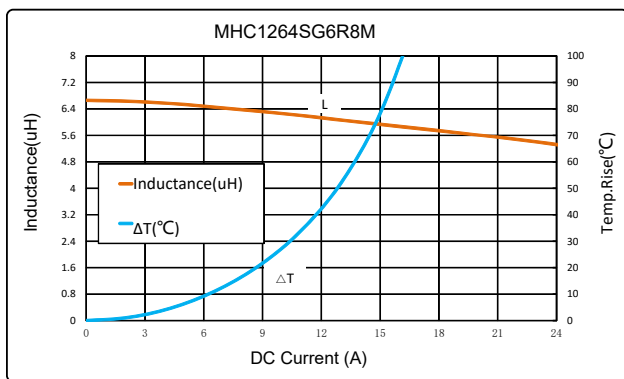
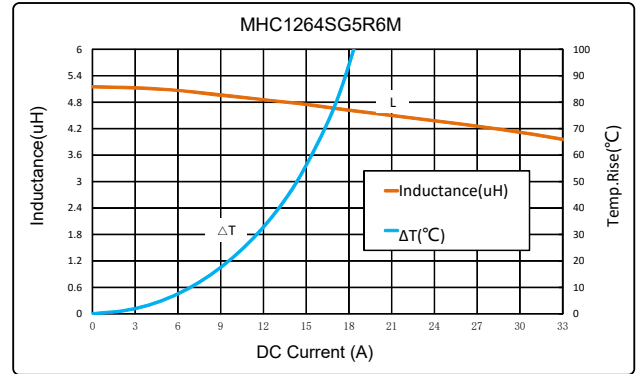
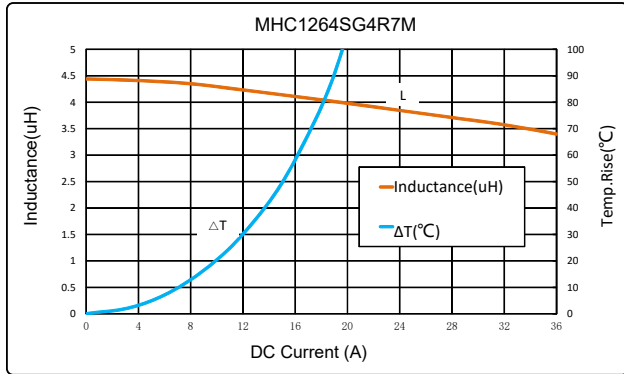
PERFORMANCE GRAPHS



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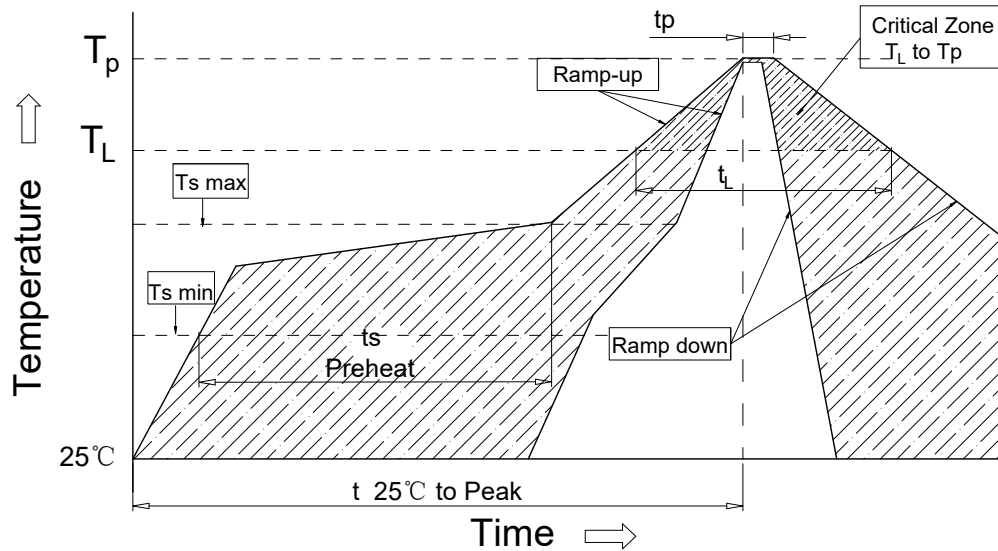


PERFORMANCE GRAPHS



1. RECOMMENDED SOLDERING PROFILE:

Reflow soldering profile (According to IPC/JEDEC J-STD-020D)



Preheat & Soak

Ts min=150°C Ts max=200°C ts=60-180s

Tl = 217°C tl =60-150s

Tp= 245°C tp=20-40s

Average ramp-up rate (Tsmax to Tp): 3 °C/second max

Average ramp-down rate (Tp to Tsmax): 6 °C/second max

Time 25°C to Peak=8min max

Note:

*Solder Paste: Sn96.5Ag3.0Cu0.5

*Silkscreen thickness: 0.15mmMin

2. MOISTURE SENSITIVE LEVEL:

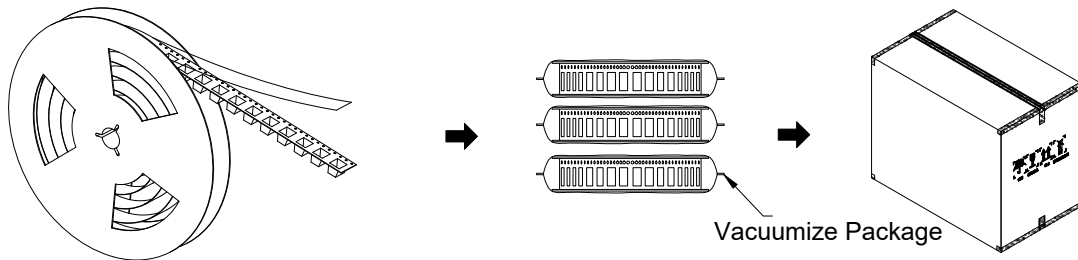
2.1. Level: 1

2.2. Floor Life: Unlimited

2.3. Storage Condition: $\leq 30^{\circ}\text{C}/85\% \text{RH}$

3.PACKING:

■ Reel:



Q'ty

300 PCS Per Reel

7 Reel Per Carton

2100 PCS Per Carton

■ Tape dimension(mm)&orientation:

